**LADEMARK OFFICE** 

Docket No.: VLSI-3370

101205088

Thereby certify that this transmittal of the below described document is being deposited with the United States Postal Service in an envelope bearing First Class Postage and addressed to the U.S. Patent and Trademark Office, Assignment Branch, North Tower Building, Suite 10C35, Washington, D.C., 20231, on the below date of deposit. Name of Person Signature of the Person

Date of

11/04/99

Making the Deposit:

TONY CHOU

Making the Deposit:

The Assistant Commissioner for Patents Washington, D.C. 20231

Deposit:

Please record the attached original document(s) or copy(ies) thereof:

Transmittal of an Assignment

1. Name of conveying Liming Zhang

party(ies):

Filed:

Serial No.:

Group Art Unit:

Examiner:

2. Name and Address of VLSI TECHNOLOGY, INC.

Receiving party(ies) 1109 McKay Drive, San Jose, CA 95131

3. Nature of Conveyance: Assignment

11/04/99

**Execution Date:** 11/03/99

4. New Patent Application entitled: AN INTEGRATED CIRCUIT (IC) PLATING DEPOSITION SYSTEM

AND METHOD

5. Name and address of party to whom correspondence concerning document should be mailed:

Name:

Glenn D. Barnes

Address

Wagner, Murabito & Hao LLP

Two North Market Street, Third Floor, San Jose, CA 95113

Phone

(408) 938-9060

6. Total Number of applications and patents involved: ONE

7. Fee Calculation (for other than a small entity)

Assignment Recordation Fee, per property

Total Fees (37 CFR 3.41)

1 X \$40.00

\$40.00

The amount of \$ 40.00 is enclosed

- 8. At any time during the pendency of this application, please charge any additional fees required or credit any overpayments to Deposit Account 23-0085. A duplicate copy of this transmittal is enclosed.
- 9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Name Glenn D. Barnes

Reg. No. 42, 293

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**PATENT** REEL: 010382 FRAME: 0208

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## Assignment to VLSI Technology, Inc.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we
Liming Zhang do hereby sell, assign and transfer unto VLSI Technology, Inc. (hereinafter called VLSI), a California Corporation having its principal place of business at 1109 McKay Drive, San Jose, California 95131, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled:
AN INTEGRATED CIRCUIT (IC) PLATING DEPOSITION SYSTEM AND METHOD
x filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; or
Serial No.: filed on and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore;
Further, I/we have agreed to assign to VLSI all inventions (except as otherwise limited by law) which relate to VLSI business and which were first conceived or actually reduced to practice during my/our employment by VLSI;
And for the above consideration, I/we agree promptly upon request of VLSI, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to VLSI, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by VLSI;
I/we further covenant with VLSI, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;
In witness whereof, I/we hereunto set my/our hand(s) and seal.  Inventor's Signature:  Date: 1/3/55

rev: 11/97 epn

**RECORDED: 11/04/1999** 

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